CLAIMS

What is claimed is:

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2	first and second elementary printed circuit boards (PCBs) spacedly positioned apart from
3	one another and each including a lower outer surface;
4	first and second electrical connectors positioned on said lower outer surfaces of said first
5	and second PCBs, respectively, at least one of said electrical connectors including
5	external pins positioned within the respective one of said PCBs on which said at least one
Ť	electrical connector is positioned; and
	an insulative layer located substantially between said first and second PCBs and in

An electronic board that assembly comprising:

an insulative layer located substantially between said first and second PCBs and in physical contact therewith, said insulative layer being flexible.

- The electronic board assembly of claim 1 further comprising at least one conductive via 2. within said insulative layer for transmitting electrical signals from one of said elementary PCBs to the other.
- 1 3. The electronic board assembly of claim 1 wherein said insulative layer includes at least 2 one conductive part therein.

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- 1 4. An electronic board assembly comprising:
- first and second elementary printed circuit boards (PCBs) spacedly positioned apart from one another and each including a lower outer surface;
 - first and second electrical connectors positioned on said lower outer surfaces of said first and second PCBs, respectively, at least one of said electrical connectors including external pins positioned within the respective one of said PCBs on which said at least one electrical connector is positioned; and
 - an insulative adhesive layer located substantially between said first and second PCBs and in physical contact therewith, said insulative layer being flexible.
 - 5. The electronic board assembly of claim 4 further comprising at least one conductive via within said insulative layer for transmitting electrical signals from one of said elementary PCBs to the other.
 - 6. The electronic board assembly of claim 4 wherein said insulative layer includes at least one conductive part therein.
- 1 7. An electronic board assembly comprising:
- first and second elementary printed circuit boards (PCBs) spacedly positioned apart from one another at a predetermined distance and each including a lower outer surface;
- first and second electrical connectors positioned on said lower outer surfaces of said first
 and second PCBs, respectively, at least one of said electrical connectors including
 external pins positioned within the respective one of said PCBs on which said at least one
 electrical connector is positioned;

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- an insulative adhesive layer located substantially between said first and second PCBs and in physical contact therewith, said insulative layer being flexible; and
- at least one mechanical member for maintaining said first and second elementary PCBs spacedly apart said predetermined distance from one another.
 - 8. The electronic board assembly of claim 7 wherein said at least one mechanical member comprises a U-shaped member positioned on the first and second electrical lower edge of each of said PCBs and having an upper part, said upper part of said U-shaped member being positioned substantially between said first and second electrical connectors carried by said two elementary PCBs.
 - 9. The electronic board of claim 8 wherein said U-shaped member is comprised of conductive material to thereby reduce electromagnetic emissions from said PCBs.
 - 10. The electronic board assembly of claim 7 further comprising at least one conductive via within said insulative layer for transmitting electrical signals from one of said elementary PCBs to the other.
 - 11. The electronic board assembly of claim 7 wherein said insulative layer includes at least one conductive part therein.
- 1 12. An electronic board assembly comprising:
- first and second elementary printed circuit boards (PCBs) spacedly positioned apart from one another and each including a lower outer surface;

first and second electrical connectors positioned on said lower outer surfaces of said first
and second PCBs, respectively, at least one of said electrical connectors including
external pins positioned within the respective one of said PCBs on which said at least one
electrical connector is positioned;

- an insulative adhesive layer located substantially between said first and second PCBs and in physical contact therewith, said insulative layer being flexible; and
- a backplane PCB having first and second electrical connectors spacedly positioned thereon, said first and second electrical connectors on said PCBs being electrically coupled to said first and second electrical connectors of said backplane PCB, respectively.
- 13. The electronic board assembly of claim 12 wherein said first and second electrical connectors on said backplane PCB are male pin connectors and said first and second electrical connectors on said first and second PCBs are female connectors.
- 14. The electronic board assembly of claim 12 further comprising at least one conductive via within said insulative layer for transmitting electrical signals from one of said elementary PCBs to another.
- 1 15. The electronic board assembly of claim 12 wherein said insulative layer includes at least 2 one conductive part therein.